Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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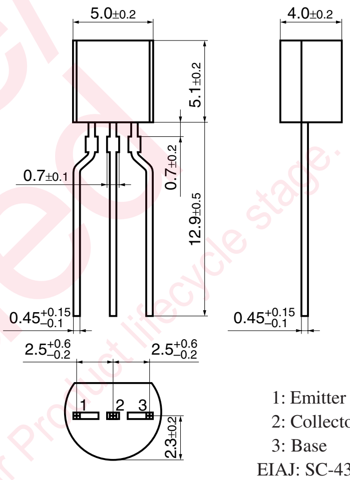
2SA0720A (2SA720A)

Silicon PNP epitaxial planar type

For low-frequency driver amplification
Complementary to 2SC1318A

Unit: mm



1: Emitter
2: Collector
3: Base
EIAJ: SC-43A
TO-92-B1 Package

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- Optimum for the driver stage of a low-frequency and 25 W to 30 W output amplifier

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	–80	V
Collector-emitter voltage (Base open)	V_{CEO}	–70	V
Emitter-base voltage (Collector open)	V_{EBO}	–5	V
Collector current	I_C	– 0.5	A
Peak collector current	I_{CP}	–1	A
Collector power dissipation	P_C	625	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

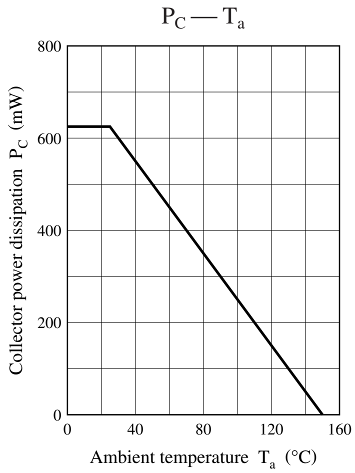
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

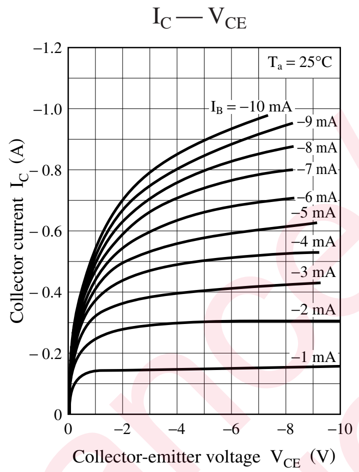
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = –10\ \mu A, I_E = 0$	–80			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = –2\ mA, I_B = 0$	–70			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = –10\ \mu A, I_C = 0$	–5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = –20\ V, I_E = 0$			– 0.1	μA
Forward current transfer ratio *1	h_{FE1} *2	$V_{CE} = –10\ V, I_C = –150\ mA$	85		240	—
	h_{FE2}	$V_{CE} = –10\ V, I_C = –500\ mA$	40			—
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = –300\ mA, I_B = –30\ mA$		– 0.2	– 0.6	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = –300\ mA, I_B = –30\ mA$		– 0.85	–1.50	V
Transition frequency	f_T	$V_{CB} = –10\ V, I_E = 50\ mA, f = 200\ MHz$		120		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = –10\ V, I_E = 0, f = 1\ MHz$		20	30	pF

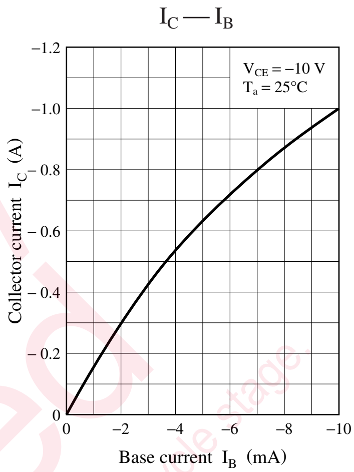
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *1: Pulse measurment
*2: Rank classification

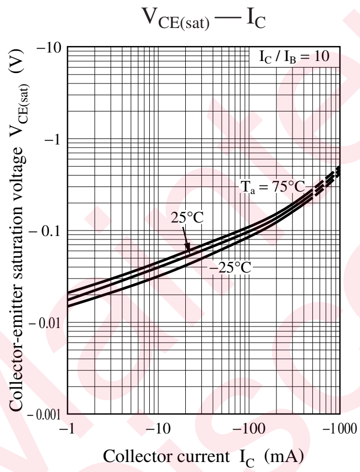
Rank	Q	R
h_{FE1}	85 to 170	120 to 240

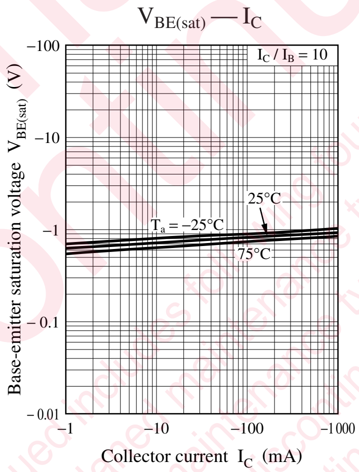
Note) The part number in the parenthesis shows conventional part number.

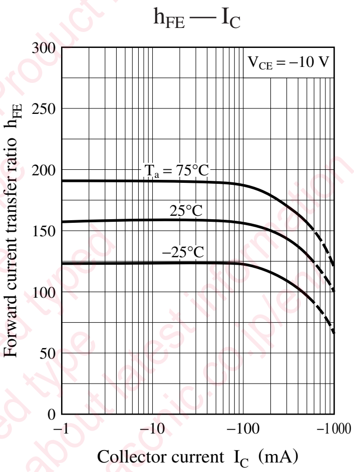


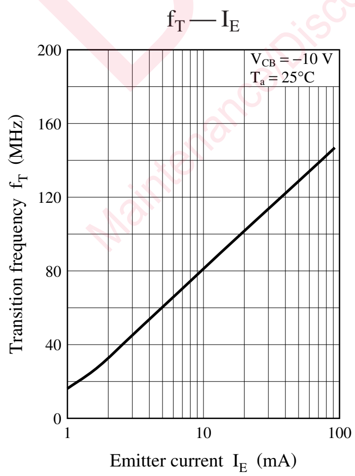


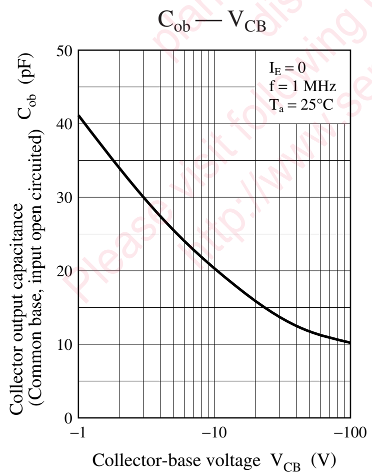


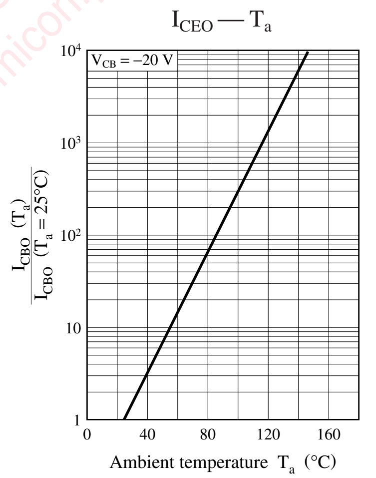












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